

CLAIMS

1. A wire saw apparatus comprising:
 - a plurality of wire guides;
 - a wire row formed of a wire which is wound around the plurality of wire guides and configured to reciprocatively travel in an axial direction;
 - a nozzle configured to supply a coolant or slurry to the wire;
 - a workpiece-holding portion configured to suspend and hold a workpiece plate having a workpiece bonded thereto with a beam interposed therebetween;
 - a workpiece-feeding mechanism configured to press the workpiece against the wire row; and
 - a mechanism comprising an adjustment bolt configured to adjust a parallelism of axes of the plurality of wire guides around which the wire row is formed, and enabling the wire saw apparatus to control a warp in a wire travelling direction of the workpiece after slicing.
2. A method for manufacturing a wafer by using the wire saw apparatus according to claim 1, comprising:
 - adjusting a parallelism of the axes of the plurality of wire guides around which the wire row is formed, before a workpiece is sliced, to control a warp in a wire travelling direction of the sliced workpiece.
3. A method for manufacturing a wafer, comprising:
 - forming a wire row by winding a wire around a plurality of wire guides, wherein the wire is configured to reciprocatively travel in an axial direction; and
 - causing a workpiece-feeding mechanism to press a

workpiece held by a workpiece-holding portion against the wire row to slice the workpiece, while supplying a coolant or slurry from a nozzle to the wire, wherein

a parallelism of axes of the plurality of wire guides around which the wire row is formed is adjusted, before the workpiece is sliced, to control a warp in a wire travelling direction of the sliced workpiece.